

**IN THE CLAIMS:**

Please amend the claims as follows:

1 – 29. (Cancel)

30. (Currently Amended) A drive electronics for driving an optoelectronic device with a matrix of picture elements, having a drive circuit ~~(102x)~~, wherein :

the drive circuit has input terminals ~~(110)~~ and output terminals ~~(112)~~;

a first arrangement of contact areas ~~(104)~~ connected with the input terminals of the drive circuit ~~(102x)~~; and

a second arrangement of contact areas ~~(105)~~ connected with the input terminals of the drive circuit ~~(102x)~~ directly or via another component, wherein the contact areas ~~(105)~~ of the second arrangement of contact areas are larger than the contact areas ~~(104)~~ of the first arrangement of contact areas.

31. (Currently Amended) The drive electronics according to claim 4 30, wherein:

the number of input terminals of the drive circuit ~~(102x)~~ by which the drive circuit is connected with the second arrangement of contact areas ~~(105)~~ is at most 5% of the number of output terminals of the drive circuit by which the drive circuit is connected with the control lines ~~(103x)~~ of the matrix of picture elements.

32. (Currently Amended) The drive electronics according to claim 4 30, wherein:

the first arrangement of contact areas ~~(104)~~ serves for picture generation during normal operation; and

the second arrangement of contact areas ~~(105)~~ serves for pattern generation during test mode.

33. (Currently Amended) The drive electronics according to claim 4 30, wherein:

the second arrangement of contact areas (105) is connected with the drive circuit (102x) via the first arrangement of contact areas (104).

34. (Currently Amended) The drive electronics according to claim [[4]] 33, wherein:  
the second arrangement of contact areas (105) is connected with the drive circuit (102x) via the first arrangement of contact areas (104) by means of switching elements or components.

35. (Currently Amended) The drive electronics according to claim [[4]] 33, wherein:  
the second arrangement of contact areas (105) is directly connected with the drive circuit (102x) via the first arrangement of contact areas (104).

36. (Currently Amended) The drive electronics according to ~~any of~~ claim 4 30, wherein:

the second arrangement of contact areas (105) is connected with the drive circuit (102x) via a test electronics (202x).

37. (Currently Amended) The drive electronics according to ~~any of~~ claim 4 30, wherein:

the second arrangement of contact areas (105) is directly connected with the drive circuit.

38. (Currently Amended) The drive electronics according to claim 8 37, wherein:  
test circuits are integrated into the drive circuit.

39. (Currently Amended) The drive electronics according to claim 4 30, wherein:  
the number of second pads (105b) of the second arrangement of contact areas (105) is at most 90% of the number of first pads (104b) of the first arrangement of contact areas (104), ~~preferably at most 50%, more preferably at most 20%~~.

40. (Currently Amended) The drive electronics according to claim 4 30, wherein:

the second pads (105b) of the second arrangement of contact areas are larger than the first pads (104b) of the first arrangement of contact areas.

41. (Currently Amended) The drive electronics according to claim 4 30, wherein: the second pads (105b) of the second arrangement of contact areas have a dimension of at least 100  $\mu\text{m}$  , ~~preferably a dimension of 0.5 mm, and more preferably a dimension of 2 mm.~~

42. (Currently Amended) An arrangement of test contact areas for providing signals for generating a test pattern to an optoelectronic device comprising a matrix of picture elements, ~~having comprising~~:

at least one pad (105b);

at least one connection (105a) of the at least ~~on~~ one pad with a drive circuit (102x) directly or via another component, which is provided with signals via an arrangement of operational contact areas (104) during normal operation;

wherein the ~~contact areas (105) of the second arrangement of test~~ contact areas are larger than the arrangement of operational contact areas (104) of the ~~first arrangement of contact areas~~.

43. (Currently Amended) The arrangement according to claim 13 42, wherein: the drive circuit has input terminals (110) and output terminals (112), and wherein the at least one connection (105a) is connected with at least one of the input terminals (110).

44. (Currently Amended) The arrangement according to claim 13 42, wherein: the at least one pad of the arrangement of contact areas has a dimension of at least 100  $\mu\text{m}$  , ~~preferably a dimension of 0.5 mm, and more preferably a dimension of 2 mm.~~

45. (Currently Amended) The arrangement according to claim 13 42, wherein:

the number of pads (105b) of the arrangement of test contact areas (105) is at most 90% of the number of pads (104b) of the arrangement of operational contact areas (104), ~~preferably at most 50%, and more preferably at most 20%~~.

46. (Currently Amended) The arrangement according to claim 13 42, wherein:  
the arrangement of test contact areas (105) is connected with the drive circuit (102x) via the arrangement of operational contact areas (104).

47. (Currently Amended) The arrangement according to claim 13 42, wherein:  
the arrangement of test contact areas is connected with the drive circuit (102x) via a test electronics (202x).

48. (Currently Amended) The arrangement according to claim 13 42, wherein:  
the arrangement of test contact areas is directly connected with the drive circuit (102x).

49. (Currently Amended) An optoelectronic device, having comprising:  
a matrix of picture elements (101); and  
a drive electronics according to any of claim 1 30.

50. (Currently Amended) A method for testing an optoelectronic device, comprising the steps of :

a) making contact is made between an external control and an arrangement of test contact areas which are larger than operational contact areas;  
b) providing an input terminal of a drive circuit is provided directly or via another component with input signals via the arrangement of test contact areas to generate a test pattern on a matrix of picture elements; and  
c) testing the picture elements of the matrix of picture elements are tested.

51. (Currently Amended) The testing method according to claim 24 50, wherein:  
the input signals generate a periodic test pattern.

52. (Currently Amended) The testing method according to claim 24 50, wherein:  
the input signals generate a vertically, horizontally or diagonally periodic test pattern.
53. (Currently Amended) The testing method according to claim 24 50, wherein:  
the picture elements are tested with a beam of charged particles or laser radiation.
54. (Currently Amended) The testing method according to claim 24 50, comprising the further step of:  
a vacuum is generated in the vicinity of the optoelectronic device to be tested.
55. (Currently Amended) The testing method according to claim 24 50, wherein step c) comprises the following steps:
  - c1) the picture elements in a portion of the matrix of picture elements are tested;
  - c2) the optoelectronic device is shifted; and
  - c3) the picture elements in a further portion of the matrix of picture elements are tested.
56. (Currently Amended) A method for manufacturing a drive electronics of an optoelectronic device having a matrix of picture elements, comprising ~~the steps~~ :
  - a) providing a drive circuit ~~is provided~~;
  - b) connecting control lines of the matrix of picture elements ~~are connected~~ with output terminals of the drive circuit;
  - c) providing a first arrangement of contact areas ~~is provided~~;
  - d) connecting the first arrangement of contact areas ~~is connected~~ with input terminals of the drive circuit;

- e) providing a second arrangement of contact areas ~~is provided~~, said second arrangement of contact areas being larger than the contact areas of said first arrangement of contact areas; and
- f) connecting the second arrangement of contact areas ~~is connected~~ with input terminals of the drive circuit directly or via another component.

57. (Currently Amended) An optoelectronic device, which has been tested by a testing method according to claim 24 50 or by an apparatus according to claim 4 30.

58. (New) An optoelectronic device according to claim 49, wherein at least parts of the second arrangement of contact areas are removed.